

558-10-356M26-001104 Information


For Reference Only

Part Number [558-10-356M26-001104](#)
Manufacturer Preci-Dip
Category Connectors, Interconnects
[Sockets for ICs, Transistors](#)
Description BGA SURFACE MOUNT 1.27MM
Package -
 For the pricing/inventory/lead time, please contact us
 Website: <https://www.heisener.com>
 E-mail: salesdept@heisener.com


[Request a Quote](#)
Certified Quality

Heisener's commitment to quality has shaped our processes for sourcing, testing, shipping, and every step in between. This foundation underlies each component we sell.


558-10-356M26-001104 Specifications

Manufacturer Part Number	558-10-356M26-001104
Manufacturer	Preci-Dip
Category	Connectors, Interconnects Sockets for ICs, Transistors
Package	-
Series	558
Type	BGA
Number of Positions or Pins (Grid)	356 (26 x 26)
Pitch - Mating	0.050" (1.27mm)
Contact Finish - Mating	Gold
Contact Finish Thickness - Mating	10µin (0.25µm)
Contact Material - Mating	Brass
Mounting Type	Surface Mount
Features	Closed Frame
Termination	Solder
Pitch - Post	0.050" (1.27mm)
Contact Finish - Post	Gold
Contact Finish Thickness - Post	10µin (0.25µm)
Contact Material - Post	Brass
Housing Material	FR4 Epoxy Glass
Operating Temperature	-55°C ~ 125°C

[Report errors?](#)

558-10-356M26-001104 Guarantees



Quality Guarantees

We provide 90 days warranty. *

If the items you received were not in perfect quality, we would be responsible for your refund or replacement, but the items must be returned in their original condition.



Service Guarantees

We guarantee 100% customer satisfaction.

Our experienced sales team and tech support team back our services to satisfy all our customers.

558-10-356M26-001104 Payment Methods



558-10-356M26-001104 Shipping Methods



If you have any question about 558-10-356M26-001104, please do not hesitate to contact us!

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